

## WIREBOND TRAINING COURSES

Inseto is now offering an extensive range of certified Wirebond **TRAINING** courses to customers.

Training provided in all fields of Microelectronics Wire Bonding:

- **BALL** bonding
- **WEDGE** bonding (small and large diameters)
- **RIBBON** bonding (Au, Al)

Inseto can offer **IN HOUSE** training courses on Bond Theory, bonder Operation, Programming and Maintenance, along with Process Development and Optimisation through the use of qualitative and quantitative methods.

Inseto offer the use of our in house materials testing and plasma cleaning capabilities as part of the in house training package. In house training also offers a closed training environment free, from the usual distractions present in the manufacturing environment.

Where specific equipment training is required, Inseto can offer **ON SITE** training directly. Bond Theory, Operation, Programming and Maintenance; Process Development and Optimisation can all be provided at the customer site.

This option can be a real benefit for training on embedded systems or sensitive products as the Inseto team will come to you.

Course content can be **TAILORED** to exact customer requirements and may include topics such as:

- Bond Theory
- Bonding Tool Selection
- Wire Selection
- Bond Quality Control
- Process Development
- Process Optimisation
- Machine Setup
- Operation
- Maintenance & Repair

All Inseto engineers are **FACTORY TRAINED** to provide instruction in the operation and maintenance of the Wire Bonder equipment we support. Each individual trainer comes direct from industry; with over 35 years combined experience in chip and wire semiconductor assembly.



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